



Click [here](#) for the 3D model.

Dimensions	
D	10.16mm +/-0.635mm
L	6.35mm MIN
H	2.54mm NOM
F	1.397mm +/-0.25mm
A	5.3mm MAX
B	7.078mm MAX
C	10.16mm +/-0.635mm
E	11.18mm MAX
K	0.5mm NOM

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	50

General Information	
Series	KPS-MCC Indust COG HT200C
Style	Leaded Stacked Chip
Description	Low ESR, Stacked Ceramic Chips
Features	200C, Low ESR, High Thermal Stability, Bulk Capacitance
RoHS	No
Prop 65	<b>⚠ WARNING:</b> Cancer and reproductive harm - <a href="http://www.p65warnings.ca.gov">http://www.p65warnings.ca.gov</a> .
SCIP Number	89f79324-98a2-425d-914d-1725e977d89a
Termination	60/40 Solder Coated
Lead	Straight Leads
AEC-Q200	No
Notes	Number of chips in this stack: 2.

Specifications	
Capacitance	0.12 uF
Capacitance Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1200 VDC
Temperature Range	-55/+200°C
Temperature Coefficient	COG
Dissipation Factor	0.1% 1kHz 25C
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	8.33 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.